



ULTRA® 3SP™ and 3SP™ High Definition

EnvisionTEC's ULTRA® 3SP™ Series 3D printers use ground-breaking 3SP™ (Scan, Spin and Selectively Photocure) technology to quickly 3D print highly accurate parts from STL files regardless of the geometric complexity. The ULTRA® 3SP™ and 3SP™ High Definition are each delivered and installed with all the relevant software to enable automatic generation of supports and perfect model production. The surface quality of the printed models show no signs of stairstepping on the inner and outer surfaces. The reliability of the imaging light source and the high speed productivity makes it the most competitive 3D printer on the market today.

Machine Properties *	ULTRA® 3SP	ULTRA® 3SP High Definition
Build Envelope	10.5" x 7" x 7.6" (266 x 177.8 x 193 mm)	10.5" x 7" x 7.6" (266 x 177.8 x 193 mm)
Resolution in X and Y	0.004" (100 µm)	0.002" (50 µm)
Dynamic Voxel Resolution in Z (User Adjustable and Material Dependent)**	0.001" - 0.004" (25 - 100 µm)	0.001" - 0.004" (25 - 100 µm)
Data Handling	STL	STL
Warranty	1 Year Included	1 Year Included

* Specifications are subject to change without notice. ** A voxel is a volumetric pixel.



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Materials Available	Ideal for
E-Denstone 3SP™	General purpose, high temperature molding, concept models
ABS-3SP™ White	Rigid, stable models imilar to those made with ABS plastic
E-Glass 3SP™	Strong, clear material with flexible capabilities

System Properties

- » A single material is used for both build and support
- » Easily removable, partially cured perforated supports
- » Very few moving parts make the system user-serviceable
- » Office friendly plug-and-play operation with a built-in touch screen
- » Extremely reliable system utilizing 3SP™ (Scan, Spin, and Selectively Photocure) technology
- » Low part cost due to minimal material waste
- » Produce everything from concept models to functional parts
- » Layerless technology with no stair stepping on inner and outer surfaces
- » Quiet operation

Footprint (L x W x H): 29" x 30" x 46"
(74 x 76 x 117 cm)

Optional Stand (L x W x H): 29" x 30" x 25"
(74 x 76 x 64 cm)

Weight: 198 lbs (89.8 kg)

Electrical Requirements:
100-127 VAC, 50/60 Hz, single phase, 8A

